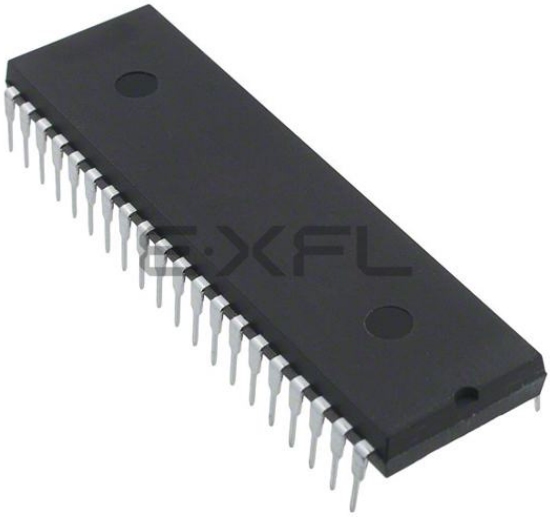

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/30MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c51ra2-vca

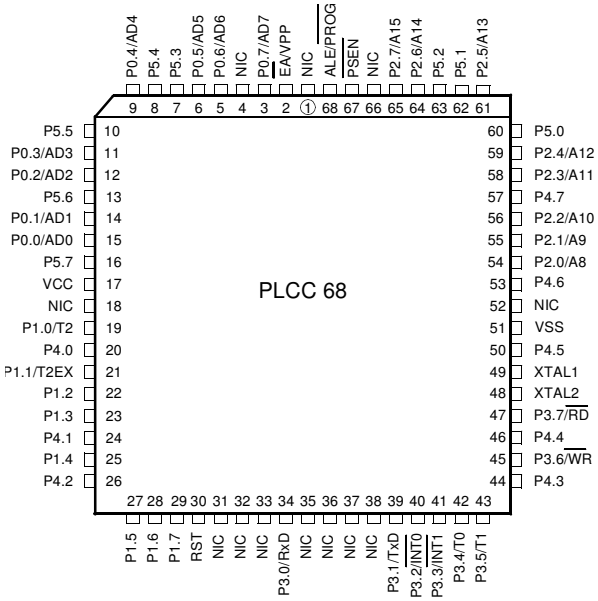
facilitates multiprocessor communication (EUART) and an X2 speed improvement mechanism.

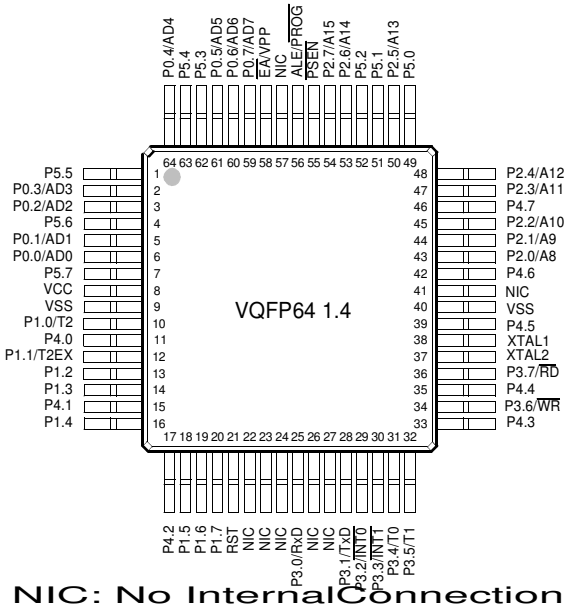
The fully static design of the TS80C51Rx2 allows to reduce system power consumption by bringing the clock frequency down to any value, even DC, without loss of data.

The TS80C51Rx2 has 2 software-selectable modes of reduced activity for further reduction in power consumption. In the idle mode the CPU is frozen while the timers, the serial port and the interrupt system are still operating. In the power-down mode the RAM is saved and all other functions are inoperative.

PDIL40 PLCC44 VQFP44 1.4	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
TS80C51RA2	0	0	256	512	32
TS80C51RD2	0	0	768	1024	32
TS83C51RB2	16k	0	256	512	32
TS83C51RC2	32k	0	256	512	32
TS83C51RD2	64k	0	768	1024	32
TS87C51RB2	0	16k	256	512	32
TS87C51RC2	0	32k	256	512	32
TS87C51RD2	0	64k	768	1024	32

PLCC68 VQFP64 1.4	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
TS80C51RD2	0	0	768	1024	48
TS83C51RD2	64k	0	768	1024	48
TS87C51RD2	0	64k	768	1024	48





NIC: No Internal Connection

Mnemonic	Pin Number			Type	Name And Function
	DIL	LCC	VQFP 1.4		
V_{SS}	20	22	16	I	**Ground:** 0V reference
Vss1		1	39	I	Optional Ground: **Contact the Sales Office for ground connection.**
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	**Port 0**: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	**Port 1**: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	**ECI (P1.2):** External Clock for the PCA
	4	5	43	I/O	**CEX0 (P1.3):** Capture/Compare External I/O for PCA module 0
	5	6	44	I/O	**CEX1 (P1.4):** Capture/Compare External I/O for PCA module 1
	6	7	45	I/O	**CEX0 (P1.5):** Capture/Compare External I/O for PCA module 2
	7	8	46	I/O	**CEX0 (P1.6):** Capture/Compare External I/O for PCA module 3
	8	9	47	I/O	**CEX0 (P1.7):** Capture/Compare External I/O for PCA module 4
P2.0-P2.7	21-28	24-31	18-25	I/O	**Port 2**: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 SFR. Some Port 2 pins (P2.0 to P2.5) receive the high order address bits during EPROM programming and verification:
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Some Port 3 pins (P3.4 to P3.5) receive the high order address bits during EPROM programming and verification. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	**RXD (P3.0):** Serial input port
	11	13	7	O	**TXD (P3.1):** Serial output port

6.2 Timer 2

The timer 2 in the TS80C51RX2 is compatible with the timer 2 in the 80C52.
It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 6-2) and T2MOD register (See Table 6-3). Timer 2 operation is similar to Timer 0 and Timer 1. C/$\overline{T2}$ selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/$\overline{RL2}$ (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.

Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C51RX2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

6.2.1 Auto-reload Mode

The auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 6-2. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.

6.4 TS80C51Rx2 Serial I/O Port

The serial I/O port in the TS80C51Rx2 is compatible with the serial I/O port in the 80C52.

It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

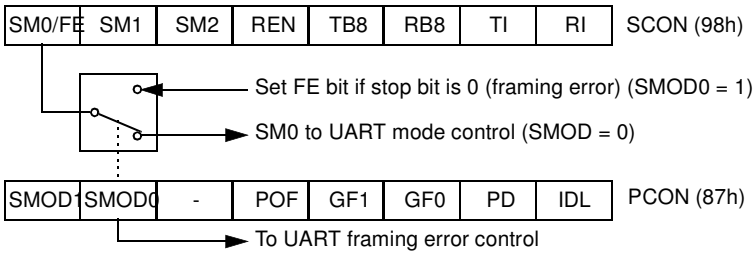
Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

6.4.1 Framing Error Detection

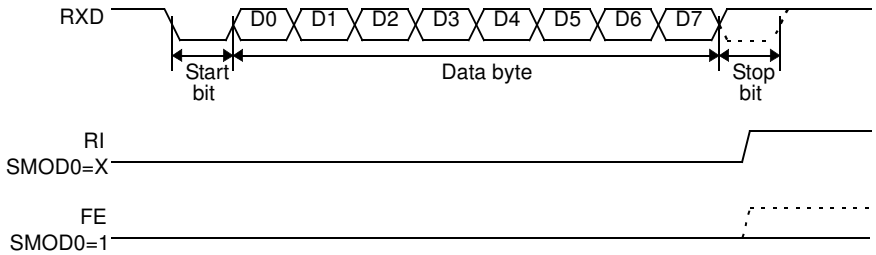
Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 6-10).

Figure 6-10. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 6-14.) bit is set.
Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 6-11 and Figure 6-12).

Figure 6-11. UART Timings in Mode 1



```
Slave C:SADDR1111 0010b
   SADEN1111 1101b
   Given1111 00X1b
```

The SADEN byte is selected so that each slave may be addressed separately.
For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

6.4.4 Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
   SADDR0101 0110b
   SADEN1111 1100b
Broadcast =SADDR OR SADEN1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b
   SADEN1111 1010b
   Broadcast1111 1X11b,

Slave B:SADDR1111 0011b
   SADEN1111 1001b
   Broadcast1111 1X11B,

Slave C:SADDR=1111 0010b
   SADEN1111 1101b
   Broadcast1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

6.4.5 Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-Off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-Down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

6.8 Hardware Watchdog Timer

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upset. The WDT consists of a 14-bit counter and the WatchDog Timer ReSeT (WDTRST) SFR. The WDT is by default disabled from exiting reset. To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, it will increment every machine cycle while the oscillator is running and there is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST-pin.

6.8.1 Using the WDT

To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, the user needs to service it by writing to 01EH and 0E1H to WDTRST to avoid WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH) and this will reset the device. When WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycle. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST-pin. The RESET pulse duration is 96 x T_{OSC} , where T_{OSC} = $1/F_{OSC}$. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

To have a more powerful WDT, a 2^7 counter has been added to extend the Time-out capability, ranking from 16ms to 2s @ F_{OSC} = 12MHz. To manage this feature, refer to WDTPRG register description, Table 6-22 (SFR0A7h).

Table 6-21. WDTRST Register
WDTRST Address (0A6h)

	7	6	5	4	3	2	1
Reset value	X	X	X	X	X	X	X

Write only, this SFR is used to reset/enable the WDT by writing 01EH then 0E1H in sequence.

Table 6-22. WDTPRG Register
WDTPRG Address (0A7h)

7	6	5	4	3	2	1	0
T4	T3	T2	T1	T0	S2	S1	S0

8.2.4 Verify Algorithm

Refer to Section “Verify algorithm”.

9. TS87C51RB2/RC2/RD2 EPROM

9.1 EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

- the code array:16/32/64 Kbytes.
- the encryption array:64 bytes.

In addition a third non programmable array is implemented:

- the signature array: 4 bytes.

9.2 EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

9.2.1 Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

9.2.2 Program Lock Bits

The three lock bits, when programmed according to Table 9-1.9.2.3, will provide different level of protection for the on-chip code and data.

Table 9-1. Program Lock bits

Program Lock Bits				
Security level	**LB1**	**LB2**	**LB3**	**Protection Description**
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed,
P: programmed

11. Electrical Characteristics

11.1 Absolute Maximum Ratings

Ambiant Temperature Under Bias: C = commercial.....0°C to 70°C I = industrial .....-40°C to 85°C Storage Temperature ..... -65°C to + 150°C Voltage on V_{CC} to V_{SS} .....-0.5 V to + 7 V Voltage on Any Pin to V_{SS}.....-0.5 V to V_{CC} + 0.5 V Power Dissipation ..... 1 W	*NOTICE: Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability. Power dissipation is based on the maximum allowable die temperature and the thermal resistance of the package.

11.2 Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

11.3 DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 11-1. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.3 0.45 1.0	V V V	I_{OL} = 100 µA (4) I_{OL} = 1.6 mA (4) I_{OL} = 3.5 mA (4)
V_{OL1}	Output Low Voltage, port 0 (6)			0.3 0.45 1.0	V V V	I_{OL} = 200 µA (4) I_{OL} = 3.2 mA (4) I_{OL} = 7.0 mA (4)
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 µA (4) I_{OL} = 1.6 mA (4) I_{OL} = 3.5 mA (4)

11.4 DC Parameters for Low Voltage

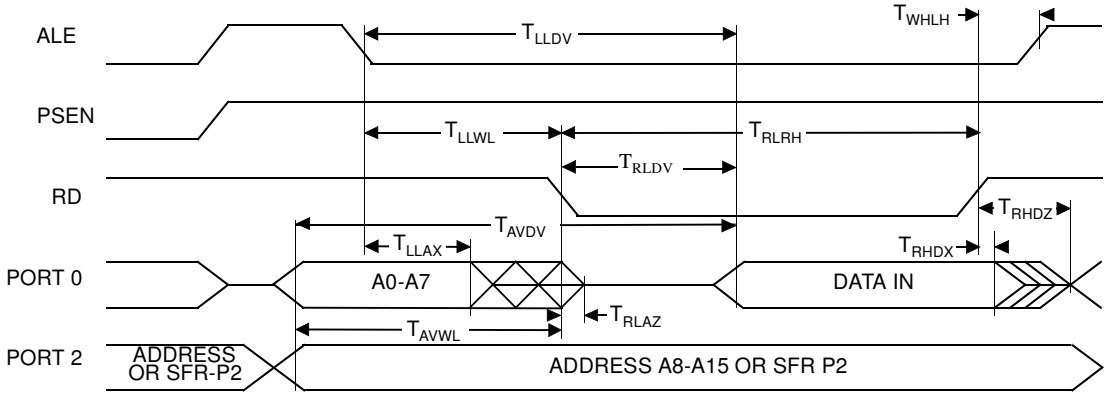
T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

Table 11-2. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power-down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5 V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{PD}	Power-down Current (Only for TS87C51RD2 S287-xxx Very Low power)		2 (5)	15	µA	2.0 V < V_{CC} < 3.6 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V_{CC} = 3.3 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	V_{CC} = 3.3 V(2)

Notes:
1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 11-5.), V_{IL} = V_{SS} + 0.5 V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..
2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 11-3.).
3. Power-down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 11-4.).

Figure 11-8. External Data Memory Read Cycle



11.5.7 Serial Port Timing - Shift Register Mode

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 11-10. AC Parameters for a Fix Clock

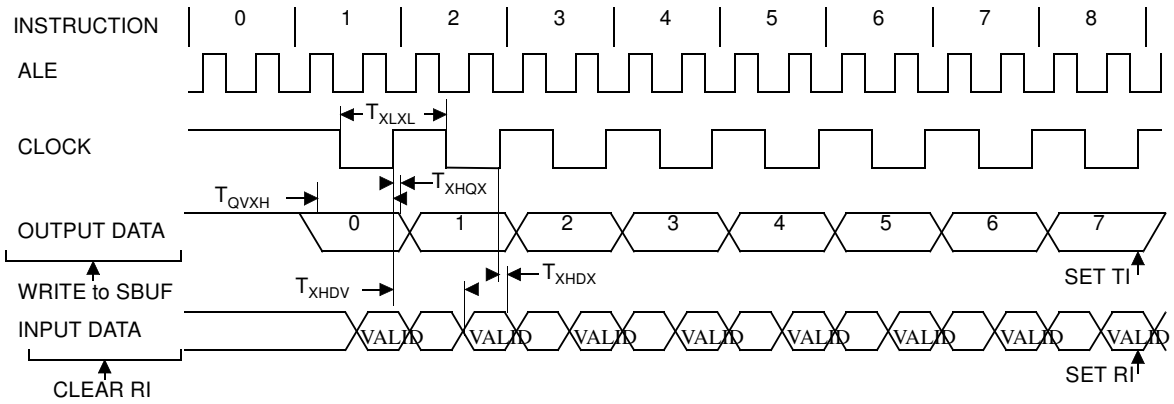
Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

Table 11-11. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T_{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T_{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T_{XHDX}	Min	x	x	0	0	0	ns
T_{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

11.5.8 Shift Register Timing Waveforms

Figure 11-9. Shift Register Timing Waveforms

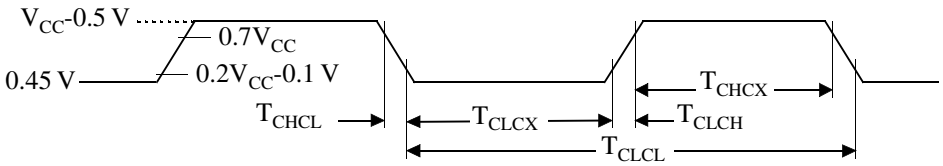


11.5.11 External Clock Drive Characteristics (XTAL1)

Symbol	Parameter	Min	Max	Units
T_{CLCL}	Oscillator Period	25		ns
T_{CHCX}	High Time	5		ns
T_{CLCX}	Low Time	5		ns
T_{CLCH}	Rise Time		5	ns
T_{CHCL}	Fall Time		5	ns
T_{CHCX}/T_{CLCX}	Cyclic ratio in X2 mode	40	60	%

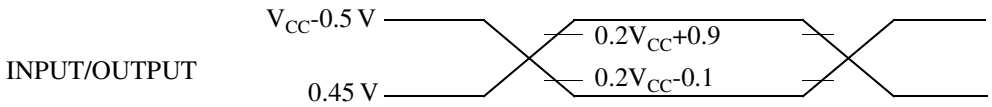
11.5.12 External Clock Drive Waveforms

Figure 11-11. External Clock Drive Waveforms



11.5.13 AC Testing Input/Output Waveforms

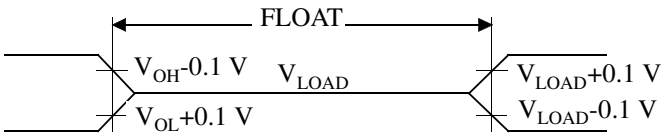
Figure 11-12. AC Testing Input/Output Waveforms



AC inputs during testing are driven at V_{CC} - 0.5 for a logic “1” and 0.45V for a logic “0”. Timing measurement are made at V_{IH} min for a logic “1” and V_{IL} max for a logic “0”.

11.5.14 Float Waveforms

Figure 11-13. Float Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \geq \pm$ 20mA.

12. Ordering Information

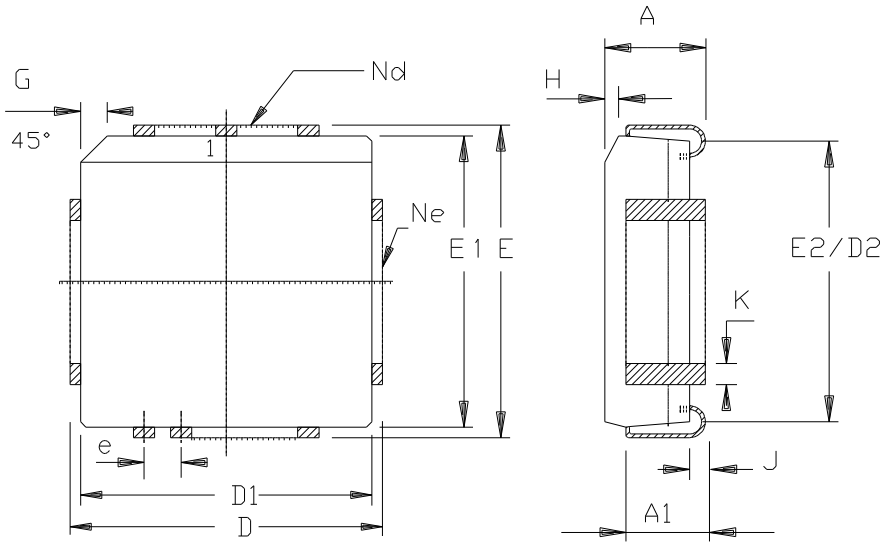
Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS80C51RA2-MCA	OBSOLETE					
TS80C51RA2-MCB						
TS80C51RA2-MCE						
TS80C51RA2-MIA						
TS80C51RA2-MIB						
TS80C51RA2-MIE						
TS80C51RA2-LCA						
TS80C51RA2-LCB						
TS80C51RA2-LCE						
TS80C51RA2-LIA						
TS80C51RA2-LIB						
TS80C51RA2-LIE						
TS80C51RA2-VCA						
TS80C51RA2-VCB						
TS80C51RA2-VCE						
TS80C51RA2-VIA						
TS80C51RA2-VIB						
TS80C51RA2-VIE						
AT80C51RA2-3CSUM	Romless	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT80C51RA2-SLSUM	Romless	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT80C51RA2-RLTUM	Romless	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT80C51RA2-3CSIM	OBSOLETE					
AT80C51RA2-SLSIM						
AT80C51RA2-RLTIM						
AT80C51RA2-3CSCL						
AT80C51RA2-SLSCL						
AT80C51RA2-RLTCL						
AT80C51RA2-3CSUL	Romless	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PDIL40	Stick
AT80C51RA2-SLSUL	Romless	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT80C51RA2-RLTUL	Romless	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray

Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS83C51RB2-MCA	OBSOLETE					
TS83C51RB2-MCB						
TS83C51RB2-MCE						
TS83C51RB2-MIA						
TS83C51RB2-MIB						
TS83C51RB2-MIE						
TS83C51RB2-LCA						
TS83C51RB2-LCB						
TS83C51RB2-LCE						
TS83C51RB2-LIA						
TS83C51RB2-LIB						
TS83C51RB2-LIE						
TS83C51RB2-VCA						
TS83C51RB2-VCB						
TS83C51RB2-VCE						
TS83C51RB2-VIA						
TS83C51RB2-VIB						
TS83C51RB2-VIE						
AT83C51RB2-3CSUM	ROM 32k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT83C51RB2-SLSUM	ROM 32k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RB2-RLTUM	ROM 32k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT83C51RB2-3CSUL	ROM 32k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PDIL40	Stick
AT83C51RB2-SLSUL	ROM 32k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RB2-RLTUL	ROM 32k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray

Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS83C51RD2-MCA	OBSOLETE					
TS83C51RD2-MCB						
TS83C51RD2-MCE						
TS83C51RD2-MIA						
TS83C51RD2-MIB						
TS83C51RD2-MIE						
TS83C51RD2-LCB						
TS83C51RD2-LCE						
TS83C51RD2-LIA						
TS83C51RD2-LIB						
TS83C51RD2-LIE						
TS83C51RD2-VCA						
TS83C51RD2-VCB						
TS83C51RD2-VCE						
TS83C51RD2-VIA						
TS83C51RD2-VIB						
TS83C51RD2-VIE						
AT83C51RD2-3CSUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT83C51RD2-SLSUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RD2-RLTUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT83C51RD2-3CSUL	ROM 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RD2-SLSUL	ROM 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray
AT83C51RD2-RLTUL	ROM 64k Bytes	5V	Industrial & Green	40 MHz (30 MHz X2)	PDIL40	Stick

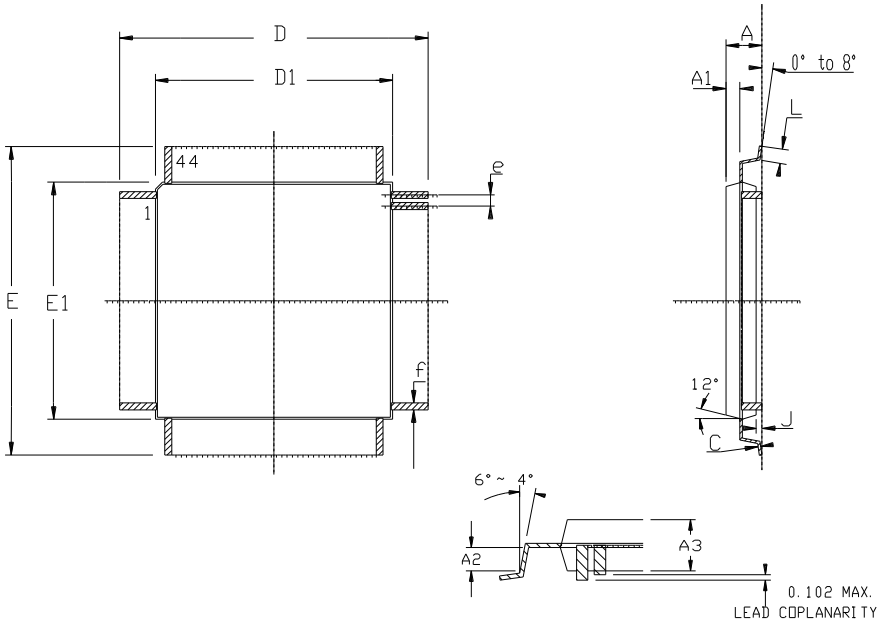
13. Package Drawings

13.1 PLCC44



	MM		INCH	
A	4.20	4.57	.165	.180
A1	2.29	3.04	.090	.120
D	17.40	17.65	.685	.695
D1	16.44	16.66	.647	.656
D2	14.99	16.00	.590	.630
E	17.40	17.65	.685	.695
E1	16.44	16.66	.647	.656
E2	14.99	16.00	.590	.630
e	1.27	BSC	.050	BSC
G	1.07	1.22	.042	.048
H	1.07	1.42	.042	.056
J	0.51	-	.020	-
K	0.33	0.53	.013	.021
Nd	11		11	
Ne	11		11	
PKG STD	00			

13.3 VQFP44



	MM		INCH	
	Min	Max	Min	Max
A	-	1.60	-	.063
A1	0.64 REF		.025 REF	
A2	0.64 REF		.025 REF	
A3	1.35	1.45	.053	.057
D	11.90	12.10	.468	.476
D1	9.90	10.10	.390	.398
E	11.90	12.10	.468	.476
E1	9.90	10.10	.390	.398
J	0.05	-	.002	-
L	0.45	0.75	.018	.030
e	0.80 BSC		.0315 BSC	
f	0.35 BSC		.014 BSC	